

120H60S

600V FRD Full Bridge Module

Features

- Repetitive Reverse Voltage: V_{RRM} = 600V
- Low Forward Voltage: V_F(typ.) = 1.5V @ I_F=120A
- Average Forward Current: $I_{F(AV)} = 120A @ T_C = 100$ °C
- Reverse Recovery Time: $t_{rr}(typ.) = 90$ ns
- Extensive Characterization of Recovery Parameters
- Reduced EMI and RFI
- · Isolation Type Package
- 150°C Operating Junction Temperature
- Built-in Full Bridge FRD Construction

Applications

- High Speed & High Power Converters, Inverter Welders
- · Various Switching and Telecommunication Power Supply
- · Cutting Machine

Description

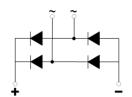
The Fast Recovery Diode module devices used Full Bridge Structure, and optimized to reduce losses and EMI/RFI in high frequency power conditioning electrical systems.

The Fast Recovery Diode module is ideally suited for power converters, inverter welders, motor drives and other applications where switching losses are significant portion of the total losses.

Package Type & Internal Circuit







Equivalent Circuit

Absolute Maximum Ratings (Per diode at T_c=25 °C unless otherwise noted)

Symbol	Parameter	r	Ratings	Unit
V_{RRM}	Repetitive Peak Reverse Voltage		600	V
V _R	DC Blocking Voltage		480	V
1	Average Rectified Forward Current	T _C = 25°C	240	۸
I _{F(AV)}		T _C = 100°C	120	A
I _{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-sine Wave		1950	А
l²t	I ² t For Fusing 60Hz Sine Wave		15.8 * 10 ³	A ² s
P_D	Maximum Power Dissipation		360	W
V _{iso}	Isolation Voltage @AC 1 Minutes		2500	V
T _J	Junction Temperature		-55 ~ +150	℃
T _{STG}	Storage Temperature		-55 ~ +150	℃
	Mounting Torque (M5)		4.0	N.m
	Terminal Torque (M5)		2.0	N.m
	Weight		137	g



$\textbf{Electrical Characteristics} \; (\text{Per diode } @T_{\text{C}}\text{=}25 \; ^{\circ}\text{C unless otherwise noted})$

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _F	Forward Voltage Drop	I _F =100A	-	1.5	1.8	V
		I _F =100A, T _C =100°C	-	1.25	-	V
I _{RM}	Reverse Leakage Current	V _R =600V	-	-	0.5	mA
		V _R =600V, T _C =100°C	-	-	1	mA
t _{rr}	Reverse Recovery Time	I _F =1A, di/dt=-200A/us	-	35	-	ns
t _{rr}	Reverse Recovery Time	I _F =100A, di/dt=-200A/us	-	90	110	ns
I _{rr}	Reverse Recovery Current		-	12	-	Α
t _{rr}	Reverse Recovery Time	I _F =100A, di/dt=-200A/us, T _C =100°C	-	220	-	ns
I _{rr}	Reverse Recovery Current		-	22	-	А

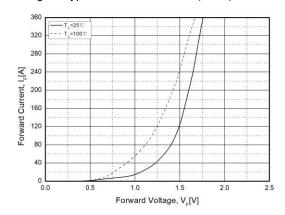
Thermal Characteristics

Symbol	Parameter	Ratings	Unit
R _{th (J-C)}	Thermal Resistance, Junction to case	0.34	°C/W



Typical Performance Characteristics

Fig. 1. Typical Characteristics: V_F vs. I_F



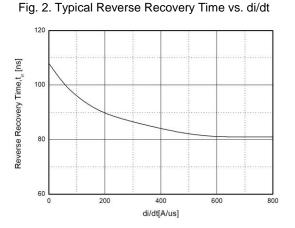


Fig. 3. Transient Thermal Impedance Characteristics ($R_{\text{th(J-C)}}$)

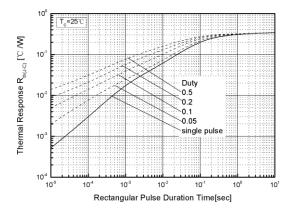
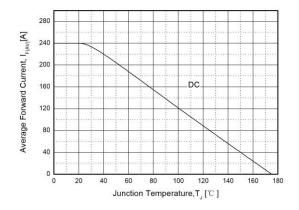


Fig. 4. Forward Current Derating Curve



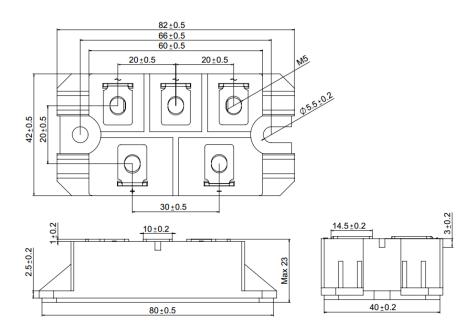


Package Dimensions

5SMDS-1



(Dimensions in Millimeters)



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